

SOLDERING CONDITIONS

□ Applicable to Chip Type Aluminum Electrolytic Capacitors

- Radial lead type and snap-in terminal type aluminum electrolytic capacitors please see titled "Mounting" in "General Information for Application".

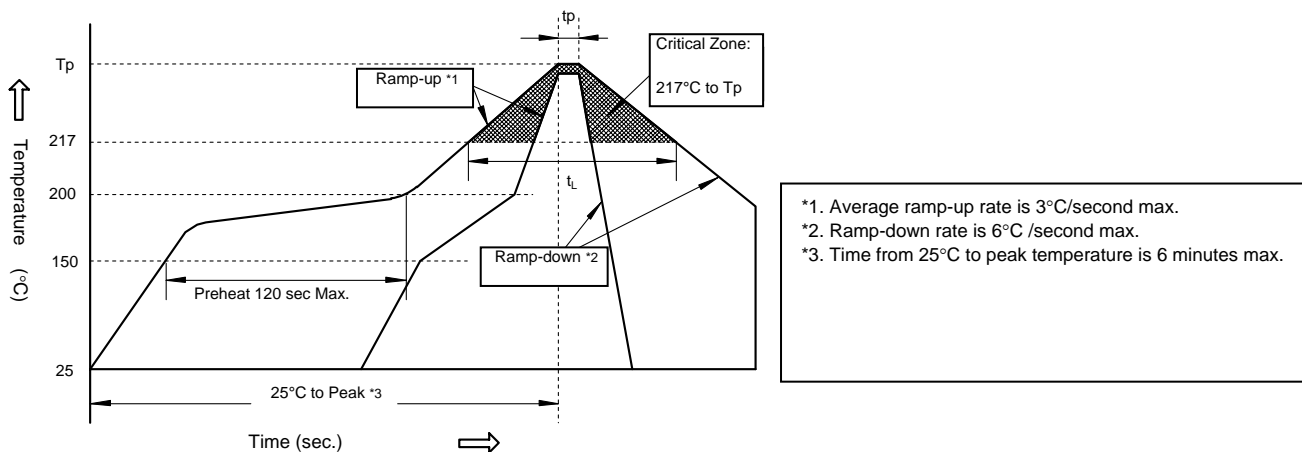
■ Recommended Conditions for Reflow Soldering

- (1) A thermal condition system such as infrared radiation (IR) or hot blast should be adopted, and vapor heat transfer systems (VPS) are not recommended.
- (2) Reflow soldering should be within 2 cycles. Please make sure that the parts have enough cooling time between the first and second soldering process.
- (3) The time of preheating from 150°C to 180°C shall be within maximum 120 seconds;

The time of soldering temperature at 217°C measured on capacitors' top shall not exceed t_L (second);

The peak temperature on capacitors' top shall not exceed T_p (°C), and the time within 5°C of actual peak temperature shall not exceed t_p (second).

■ Classification Reflow Profile

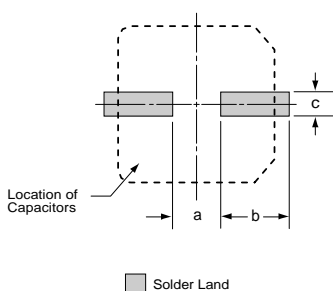


■ Classified at Temperature and Time

Size	Preheat	T_p (°C)	t_L (second)	t_p (second)	Reflow number
Ø4~Ø6.3, Ø8×6.2L	150~180°C 120s Max.	255	60	5	2 times or less
Ø8×10.5L		250	60	5	
Ø10×10.5L/13.5L		245	60	5	
Ø12.5, Ø16		240	40	5	

- Please contact us if your condition is over the maximum.

■ Recommended Solder Land Size on PC Board (Unit: mm)



Size	a	b	c
Ø4	1.0	2.6	1.6
Ø5	1.4	3.0	1.6
Ø6.3	1.9	3.5	1.6
Ø8×6.2L	2.1	4.0	1.6
Ø8×10.5L	3.0	3.5	2.5
Ø10	4.0	4.0	2.5
Ø12.5	4.0	6.0	3.2
Ø16	6.0	7.0	3.5

Note: All design and specifications are for reference only and is subject to change without prior notice. If any doubt about safety for your application, please contact us immediately for technical assistance before purchase.